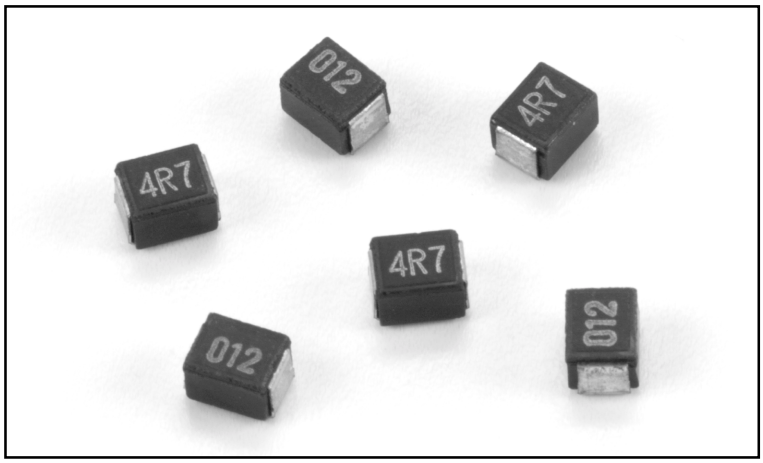
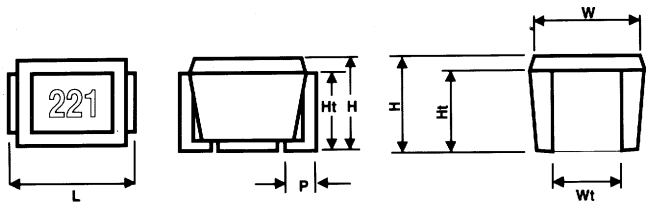


CHIP INDUCTORS

- UL94V-0 Molded Epoxy Case
- Suitable for Reflow & Wave Solder
- 1210 Size - Surface Mount Style
- E12 Series of Values
- Wound Coil Type
- SMT Lab Kit also available

DIMENSIONS

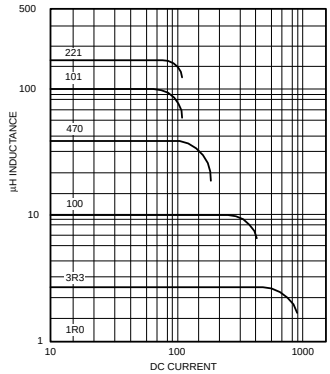


DIMENSIONS	L	W	Wt	H	Ht	P
MM	3.2 ±0.2	2.5 ±0.2	1.7 ±0.1	2.2 ±0.2	1.9 ±0.1	.50 nominal
INCH	.126 ±.008	.098 ±.008	.067 ±.004	.087 ±.008	.075 ±.004	.02 nominal

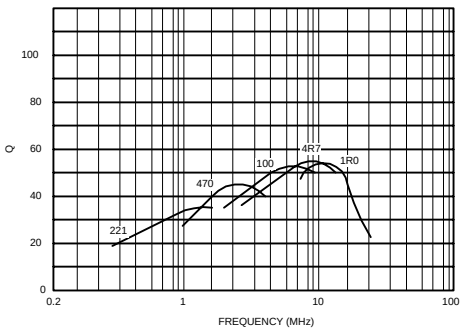
MARKING ON INDUCTOR CHIP

VALUE	CODE
0.005µH to 0.082µH	005 - 082
0.10µH to 8.2µH	R10 - 8R2 R Indicates Decimal Pt.
10µH - 330 µH	100 - 331 1st two figures are significant, the last figure indicates the number of zeros to follow

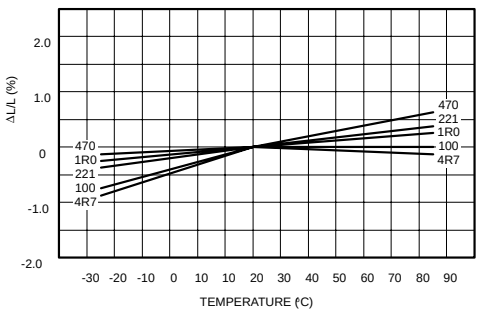
DC CURRENT CHARACTERISTICS



Q-FREQUENCY CHARACTERISTICS



TEMPERATURE CHARACTERISTICS



ORDERING & SPECIFYING INFORMATION*

KL	32	TE	101	J
Type	Size Code	Packaging	Nominal Inductance	Tolerance
	3.2x2.5x2.2 1210 Size	TE: Embossed Plastic 2000 pcs/reel TED: 10” Embossed Plastic	Value designation same as marking on Inductor Chip	J: ±5% K: ±10% M: ±20%

*Please Note: KSE’s Part Numbers Do Not Contain any Spaces or Hyphens.

STANDARD APPLICATIONS

TYPE	Ind. µH	Inductance Tolerance (%) M	K	J	Quality Factor min.MHz	SRF Res (min) MHz	DC. (max.) Ω	Allowable DC Currant mA max.	Meas. Frequency Mhz
KL32TE005*	0.005	±20			11	2700	0.12	450	100
KL32TE010*	0.010		±10		15	2500	0.13		
KL32TE012*	0.012				17	2300	0.14		
KL32TE015*	0.015				19	2100	0.16		
KL32TE018*	0.018				21	1900	0.18		
KL32TE022*	0.022				23	1700	0.20		
KL32TE027*	0.027					1500	0.22		
KL32TE033*	0.033			±5	25	1400	0.24		
KL32TE039*	0.039					1300	0.27		
KL32TE047*	0.047				26	1200	0.30		
KL32TE056*	0.056					1100	0.33		
KL32TE068*	0.068				27	1000	0.36		
KL32TE082*	0.082					900	0.40		
KL32TER10*	0.10				28	700	0.44		
KL32TER12*	0.12				30	500	0.22		25.2
KL32TER15*	0.15					450	0.25		
KL32TER18*	0.18					400	0.28		
KL32TER22*	0.22					350	0.32		
KL32TER27*	0.27					320	0.36		
KL32TER33*	0.33					300	0.40		
KL32TER39*	0.39					250	0.45		
KL32TER47*	0.47					220	0.50		
KL32TER56*	0.56					180	0.55		
KL32TER68*	0.68					160	0.60		
KL32TER82*	0.82					140	0.65		
KL32TE1R0*	1.0					120	0.70	400	7.96
KL32TE1R2*	1.2					100	0.75	390	
KL32TE1R5*	1.5					85	0.85	370	
KL32TE1R8*	1.8					80	0.90	350	
KL32TE2R2*	2.2					75	1.0	320	
KL32TE2R7*	2.7					70	1.1	290	
KL32TE3R3*	3.3					60	1.2	260	
KL32TE3R9*	3.9					55	1.3	250	
KL32TE4R7*	4.7					50	1.5	220	
KL32TE5R6*	5.6					47	1.6	200	
KL32TE6R8*	6.8					43	1.8	180	
KL32TE8R2*	8.2					40	2.0	170	
KL32TE100*	10					36	2.1	150	2.52
KL32TE120*	12					33	2.5	140	
KL32TE150*	15					30	2.8	130	
KL32TE180*	18					27	3.3	120	
KL32TE220*	22					25	3.7	110	
KL32TE270*	27					20	5.0	80	
KL32TE330*	33					17	5.6	70	
KL32TE390*	39					16	6.4	65	
KL32TE470*	47					15	7.0	60	
KL32TE560*	56					13	8.0	55	
KL32TE680*	68					12	9.0	50	
KL32TE820*	82					11	10	45	
KL32TE101*	100				20	10	10	40	0.796
KL32TE121*	120					10	11	70	
KL32TE151*	150					8	15	65	
KL32TE181*	180					7	17	60	
KL32TE221*	220					7	21	50	
KL32TE271*	270					6	28		
KL32TE331*	330					5	34		

TE: EMBOSED PLASTIC *: TOLERANCE CHARACTER (J,K,M)

ENVIRONMENTAL & MECHANICAL CHARACTERISTICS

PARAMETER	MAXIMUM △ L	TEST METHODS
Low Temperature Characteristics	No evidence of damage △ L/L within ±5% △ Q/Q within ±20%	Store at -40 ± 2°C, for 1000 hours
Resistance to Heat	No evidence of damage △ L/L within ±5% △ Q/Q within ±30%	Store at +100 ±2°C, for 1000 hours
Thermal Shock	No evidence of damage △ L/L within ±5%	100 cycles between -25°C/hour and + 100°C/hour
Temperature Characteristics	△ L/L within ±10%	△ L/L to be measured at the Temperatures between -25°C and +85°C, referenced to the inductance at 25°C
Moisture Endurance	No evidence of damage △ L/L within ±5% △ Q/Q within ±30%	Temperature 40 ± 2°C, humidity 90 - 95%, 1000 hours
Resistance to Solvents	No damage and markings must remain legible	MIL -STD - 202 Method 215
Terminal Pull Strength	No evidence of damage	Terminals shall withstand a pull of 0.5Kg in a horizontal direction
Terminal Bending Strength	No evidence of breakdown	Specimen shall be soldered and force applied to the opposite side to cause a 3mm deflection
Vibration	△ L/L shall be within ±3%	2 hours in each direction of X, Y, Z on PCB at a frequency range of 10 - 55 - 10HZ with 1.5mm amplitude
Resistance to Soldering Heat	No evidence of outer damage △ L/L shall be within ±3%	Immerse in solder at 260 ± 5°C for 10 ± 1 seconds
Solderability	95% of the terminal should be covered with new solder	Immerse in solder at 230 ± 5°C for 3 ± 0.5 seconds
DC Superimposition	△ L/L within ± 10%	When the allowable current is applied, inductance to be measured by LCR - meter
Dielectric Withstanding Voltage	No evidence of flaming, fuming, or breakdown	5 seconds at DC 1000V applied between both terminals and case.
Insulation Resistance	1000M ohm and over	1 minute at DC 500V measured between both terminals and case
Storage Temperature Range	-40°C ~ + 100°C	
Operating Temperature Range	-40°C ~ + 100°C	